

Notice of References Cited	Application/Control No. 10/765,931		Applicant(s)/Patent Under Reexamination KUKIMOTO ET AL.	
	Examiner Khiem D. Nguyen		Art Unit 2823	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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*	B	US-5,738,269	04-1998	Masterton, Patrick J.	228/248.1
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*	N	2002-334895	11-2002	Japan	Sakuyama Seiki	H01L 21/60
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NON-PATENT DOCUMENTS

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	U	Patent Abstract of Japan "Method for forming bump" Publication number 2002-334895, Sakuyama Seiki (22.11.2002), English translation.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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